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	FID1 FID2 FID3					
	SH-J3 SH-J6 SH-J8					
\vdash	SH-J3 SH-J6 SH-J8 SH-J9					
	PCB Number: PWR545 PCB	LBL1				
	PCB Number: PWR545 PCB Rev: C PCB Rev: C PCB Rev: C	PCB Label Size: 0.65" x 0.20 "				
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	ZZ1 Label Assembly Note This Assembly Note is for PCB labels only					
	ZZ2 <u>Assembly Note</u> This Assembly Note will show in the PcbDoc and associated outputs					
	ZZ3 Assembly Note This Assembly Note will show in the PcbDoc and associated outputs					
	ZZ4 <u>Assembly Note</u> This Assembly Note will show in the PcbDoc and associated outputs					
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		Texas Instruments and/or its licensor	do not warrant the accuracy or completeness of this specification or an	r information contained therein. Texas Instruments and/or its licensore do n	Designed for: Pul Project Title: bq2 Number: PWR545 Rev: C Sheet Title: ot SVN Rev: Not in version control Assembly Varian Drawn By:Casey, Jared File: PWR545C. Enrineer: Casey, Jared Contact: http://www.	blic Release Mod. Date: 2/20/2014 7/621EVM TEXAS tt: 001 Sheet: 2 of 2
	1	warrant that this design will meet the licensors do not warrant that the design 2	to not warrant the accuracy of completeness of this specification of any pecifications, will be suitable for your application or fit for any particular is production worthy. You should completely validate and test your der 3	information contained therein. Texas Instruments and/or its licensors do n purpose, or will operate in an implementation. Texas Instruments and/or its sign implementation to confirm the system functionality for your application. 4	Number: PWR545 Rev: C Sheet Title: ot SVN Rev: Not in version control Assembly Varian Drawn By: Casey, Jared File: PWR545C I Engineer: Casey, Jared Contact: http://w 5 5 5 5 5 5 5	Hardware.SchDoc Size: B http://www.ti.com ww.ti.com/support © Texas Instruments 2013
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